



DDR2 SO DIMM

TE Internal #: 1565918-4  
Double Data Rate (DDR) 2, Stack Height 5.2 mm [.205 in], Right Angle Module Orientation, 200 Position, DDR2 SO DIMM, SO DIMM Sockets

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DRAM Type: Double Data Rate (DDR) 2  
Stack Height: 5.2 mm [ .205 in ]  
Module Orientation: Right Angle  
Number of Positions: 200  
Centerline (Pitch): .6 mm [ .024 in ]

[All DDR2 SO DIMM Sockets \(28\)](#)

Features

Electrical Characteristics

|              |       |
|--------------|-------|
| DRAM Voltage | 1.8 V |
|--------------|-------|

Industry Standards

|                        |          |
|------------------------|----------|
| UL Flammability Rating | UL 94V-0 |
|------------------------|----------|

Termination Features

|                           |               |
|---------------------------|---------------|
| Insertion Style           | Cam-In        |
| Termination Method to PCB | Surface Mount |

Mechanical Attachment

|                          |                |
|--------------------------|----------------|
| Connector Mounting Type  | Board Mount    |
| PCB Mount Retention Type | Solder Peg     |
| Mating Alignment Type    | Reverse Keying |
| PCB Mount Retention      | With           |

Signal Characteristics

|               |       |
|---------------|-------|
| SGRAM Voltage | 1.8 V |
|---------------|-------|

Packaging Features

|                    |             |
|--------------------|-------------|
| Packaging Quantity | 150         |
| Packaging Method   | Tape & Reel |



Contact Features

|                                               |              |
|-----------------------------------------------|--------------|
| Contact Current Rating (Max)                  | .5 A         |
| Memory Socket Type                            | Memory Card  |
| Contact Base Material                         | Copper Alloy |
| PCB Contact Termination Area Plating Material | Gold Flash   |
| Contact Mating Area Plating Material          | Gold Flash   |

Body Features

|                        |                 |
|------------------------|-----------------|
| Latch Plating Material | Tin             |
| Latch Material         | Stainless Steel |
| Module Key Type        | SGRAM           |
| Ejector Type           | Locking         |
| Ejector Location       | Both Ends       |
| Connector Profile      | Standard        |

Housing Features

|                    |                                |
|--------------------|--------------------------------|
| Housing Material   | High Temperature Thermoplastic |
| Housing Color      | Black                          |
| Centerline (Pitch) | .6 mm[.024 in]                 |

Configuration Features

|                     |             |
|---------------------|-------------|
| Number of Bays      | 2           |
| Number of Keys      | 1           |
| Number of Rows      | 2           |
| Module Orientation  | Right Angle |
| Number of Positions | 200         |

Product Type Features

|                                   |                          |
|-----------------------------------|--------------------------|
| Connector & Contact Terminates To | Printed Circuit Board    |
| Connector System                  | Cable-to-Board           |
| DRAM Type                         | Double Data Rate (DDR) 2 |

Dimensions

|                    |                 |
|--------------------|-----------------|
| Stack Height       | 5.2 mm[.205 in] |
| Row-to-Row Spacing | 6.2 mm[.244 in] |

Usage Conditions

|                             |                           |
|-----------------------------|---------------------------|
| Operating Temperature Range | -55 – 85 °C[-67 – 185 °F] |
|-----------------------------|---------------------------|



Operation/Application

|                     |       |
|---------------------|-------|
| Circuit Application | Power |
|---------------------|-------|

Other

|                    |           |
|--------------------|-----------|
| EU RoHS Compliance | Compliant |
| EU ELV Compliance  | Compliant |

Product Compliance

For compliance documentation, visit the product page on TE.com>

|                                               |                                                                                                                                 |
|-----------------------------------------------|---------------------------------------------------------------------------------------------------------------------------------|
| EU RoHS Directive 2011/65/EU                  | Compliant                                                                                                                       |
| EU ELV Directive 2000/53/EC                   | Compliant                                                                                                                       |
| China RoHS 2 Directive MIIT Order No 32, 2016 | No Restricted Materials Above Threshold                                                                                         |
| EU REACH Regulation (EC) No. 1907/2006        | Current ECHA Candidate List: JUNE 2024 (241)<br>Candidate List Declared Against: JUNE 2024 (241)<br>Does not contain REACH SVHC |
| Halogen Content                               | Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free                                             |
| Solder Process Capability                     | Reflow solder capable to 260°C                                                                                                  |

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>

Compatible Parts





TE Part # 2309407-1  
DDR4 SODIMM 260P 4.0H STD

Also in the Series

DDR2 SO DIMM

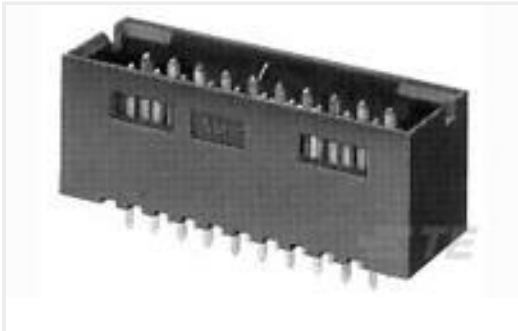


SO DIMM Sockets(24)

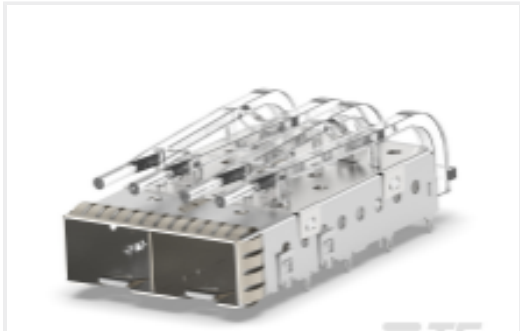
Customers Also Bought



TE Part #1554953-1  
FBIS-II PLUG ASSY 4 POS V TYPE



TE Part #5-102619-1  
06 MODII HDR DRST SHRD .100CL



TE Part #2007262-2  
SFP+ 1x2 Cage Assembly, Light

TE Part #1-2333126-2  
CAGE ASSY, QSFP -DD 1X1, STANDARD, 4LP



TE Part #2349642-2  
CAGE ASSY, 1X4, QSFP28, SPRING, HS, LP

TE Part #2-2214617-5  
SFP+assy 2x1 EMI Spring, 4LP Sn



TE Part #2016623-5  
RF CA, 1.0-2.3 TO UMCC WITH 1.37, L265MM

TE Part #2016623-6  
RF CA, 1.0-2.3 BULKHEAD TO UMCC GEN1, 1.37

TE Part #2345275-1  
Module, female guide whisper C/A Module

TE Part #2355673-1  
CA, INLET TO FLAG FAST



Documents

Product Drawings

EMBOSS ASSY DDR2 SODIMM SOCKET 200P 5.2H

English

CAD Files

Customer View Model

ENG\_CVM\_CVM\_1565918-4\_D1.2d\_dxf.zip

English

3D PDF

3D

Customer View Model

ENG\_CVM\_CVM\_1565918-4\_D1.3d\_igs.zip

English

Customer View Model

ENG\_CVM\_CVM\_1565918-4\_D1.3d\_stp.zip

English

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Product Specifications

Application Specification

English